

Technical User Forum (TUF) Meetings – Sunday, May 31, 2015

3D & VISUALIZATION TUF

Agenda

| 3D & Visualization TUF - Room 318 | | | |
|-----------------------------------|---|---|-------------------------------------|
| Time | Topic / Discussion Leader | | |
| 08:00 – 09:00 a.m. | Plenary Session | | |
| 09:00 – 09:15 a.m. | Break | | |
| | BREAKOUT 1 – ROOM 318 | BREAKOUT 2 – ROOM 301 | BREAKOUT 3 – ROOM 302 |
| 09:15 – 10:15 a.m. | Interoperability with Mechanical CAD | Piping Isometrics | SPEL/SPI/Smart 3D Cable Integration |
| 10:15 – 10:30 a.m. | Break | | |
| 10:30 – 11:30 a.m. | Administrative Improvements | Hangers and Equipment | Structure |
| 11:30 – 12:30 a.m. | TUF lunch – Room 316/317 | | |
| 12:30 – 1:30 p.m. | SPRD Integration | SmartPlant Review as a 64 bit Application | Marine Content |
| 1:30 – 1:45 p.m. | Break | | |
| 1:45 – 2:45 p.m. | Piping Design Improvements | Drawings and Reports | New Environments |
| 2:45 – 3:00 p.m. | Break | | |
| 3:00 – 4:00 p.m. | Piping Design Reuse on Diverse Project Environments | Civil Environment | Material Handling Environment |
| 4:00 – 5:00 p.m. | | | |

3D & Visualization TUF Break-out Sessions

BREAKOUT 1 – ROOM 318

Interoperability with Mechanical CAD

09:15-10:15 AM

Intergraph Sponsor: Robert Christian

Customer Sponsor: Chris Lubrano, Kiewit Power Engineers

Learn how the new native MCAD readers will improve your workflows, saving you time and money. This new module enables SmartPlant Interop Publisher 2015R1 to convert 3D models designed in Mechanical CAD applications. It reduces

the number of steps required to include equipment models in the plant by reading the natively MCAD formats from NX, Solid Edge, Solid Works, Pro/E, CATIA and Inventor. Along with graphic simplification, de-featuring, and occlusion options, engineering data found on nozzles and other connection points is collected and stored in the SPIOP format for use in Smart 3D, SmartPlant Review, SmartPlant Foundation, SmartPlant Construction, and SmartPlant Materials. Stop using heavy equipment graphics (SAT format) with no intelligence. Smaller graphics significantly improve memory management. Capturing saved intelligence helps designers. Equipment IP is protected. Workflows are improved by eliminating the need to re-model unique equipment, modules, or sub-systems.

The session will include a summary of the other new enhancements to SPIOP 2015R1 which include batch scheduling and multi user access to a remote database. Also, Smart 3D models with 2D isometric and orthographic drawings can be published through SPIOP into SmartPlant Construction.

Administration Improvements

10:30-11:30 AM

Intergraph Sponsor: Tom Szoka

Join us in the Administration Improvements breakout session where we will highlight recent and upcoming improvements in the configuration and administration of Smart 3D. New features covered will include easier migration to new versions, improved management of To Do List records, and tools to better find and repair inconsistencies in reference data. We will also open the floor up for discussions to let TUF members share their own work processes, helpful tips, and best practices to help the Smart 3D administrator.

SPRD Integration

12:30 -1:30 PM

Intergraph Sponsors: Satish Hota

Please join us in the SmartPlant Reference Data and Smart 3D Integration breakout session. Over the past year, SmartPlant Reference Data has been greatly enhanced to support component and spec creation. Further, improvements have been made to map the specs created to Smart 3D and validate them before exporting to Smart 3D. You will get details of these enhancements in this session along with an overview of the roadmap for the year to come. Subsequently, we will open the floor for discussions and solicit your valuable feedback to help guide the direction of these products to better address your needs.

Piping Design Improvements

1:45-2:45 PM

Intergraph Sponsor: Muneeb Khadeer

Improving the productivity of piping designers using Smart 3D was a major focus in our upcoming 2016 release. The enhancements we are planning make it easier for piping designers to select sections of piping, move pipe, and route pipe using a new command which lets the designer interactively choose the optimal path. Piping design is an essential piece of Smart 3D and it is our job to ensure that we continue to improve your experience with it. Please join us during our breakout session to see what we have been working on and give us your input. The main purpose for this session is to get feedback from TUF participants on the current release and prioritize items for future releases so that Intergraph can respond to your requirements. Please bring your proposals, share your user experiences, and participate in the Piping Design Improvements breakout session. Look forward to seeing you there!

Piping Design Reuse in Diverse Project Environments

3:00-4:00 PM

Intergraph Sponsor: Luther Walke

The reuse of piping designs from prior projects promises significant benefits in cost and schedule saving; however, it can bring with it significant challenges as well. This is particularly the case when piping catalog and/or symbol differences exist, for example when participating as a sub-contractor on a joint-venture project. Intergraph is adding new, sophisticated capabilities to the MDR command to help support these types of challenging workflows. Please join us in this breakout session to learn about these new capabilities and provide your feedback on the level of value you believe they will bring to your projects.

Piping Design Experience and Practice

4:00-5:00 PM

Intergraph Sponsors: Luther Walke/Tom Szoka/Bruce Wang

Join us for a joint discussion on your experiences and best practices using Smart 3D for piping design. Discussion topics include:

- Benefits/advantages seen in using Smart 3D over PDS and PDMS
- Best practices and work processes using Smart 3D for piping design
- Breakdown of roles and responsibilities for staffing and supporting a piping design team
- How to apply Smart 3D for modular design and construction

BREAKOUT 2 – ROOM 301

Piping Isometrics

09:15-10:15

Intergraph Sponsor: Jim Edwards

Please join us in the Piping Isometrics breakout session where we will look at recent developments, particularly the Isogen Configuration tool and Cable Tray Isometrics. Next, we will share our medium to long term plans. Finally, there will be an open discussion led by you, the TUF members, to explain your Piping Isometrics needs. This is your chance to connect with the Piping Isometrics experts to ask questions and influence priorities.

Hangers and Equipment

10:30-11:30 AM

Intergraph Sponsor: Brant Remenda

Customer Sponsor: Cynthia Zugelder, Kiewit Engineering Design

We invite you to attend this breakout session where we will demonstrate and discuss the latest improvements we have been working on over the last 12 months, as they relate to the Hangers and the Equipment Tasks. We will then open up the floor to listen to what direction users and potential users would like to see the product functionality take. Don't miss this opportunity to ask questions and let Intergraph know your priorities.

SmartPlant Review as a 64 bit Application

12:30 -1:30 PM

Intergraph Sponsor: Robert Christian

Customer Sponsor: Chris Lubrano, Kiewit Power Engineers

Learn how SmartPlant Review, as a large model viewer (64 bit application), will enable you to perform productive design review sessions on the largest projects by taking full advantage of all available memory and processing power on the latest hardware. Also see the new capabilities available in the Photo-Realism module that provide real-time shadowing and lighting capabilities that improve image quality. Performance improvements will help every in design review. Discussions will include improvements to the new Intergraph FreeView for the iPad and PC as well.

Drawings and Reports

1:45 – 2:45 PM

Intergraph Sponsor: Nikhil Gaonkar

Please join us in the Drawings & Reports breakout session where we will begin by discussing the enhancements made in the last year in our V2014 R1 release as well as new features being developed for our next major release. These features include the ability to use issues and revisions from the tool instead of SPF and improvements to manual touch up workflows. We will then open up the discussion to TUF members on your experiences with Drawings and Reports creation and administration to make sure Intergraph's plans line up with your needs.

Civil Environment

3:00 - 4:00 PM

Intergraph Sponsor: Joe Harrison

Customer Sponsor: Joao-Carlos Pereira-Fialho, Technip

Don't miss this chance to see and hear about the newest additions to the Civil Environment. Since it was introduced at our last HxGN Live conference, many new features and improvements have been added to support downstream enterprise solutions, enable Global Workshare, produce new drawings and reports, and increase modeling ease. Learn more about these improvements and how they help facilitate you work in other tools such as SmartPlant Foundation, SmartPlant Construction, SmartPlant Interop Publisher, and SmartPlant Review. Your active participation will also be helpful in reviewing and guiding the Civil Roadmap.

BREAKOUT 3 – ROOM 302

SPEL/SPI/S3D Cable Integration

9:15-10:15 AM

Intergraph Sponsor: Muneeb Khadeer

SPEL/SPI/S3D Cable Integration is an essential piece of the Integration workflow, and it is our job to ensure that we continue to improve your experience with Cable Integration. We are planning some exciting new enhancements and would like to share them with you during this session. Please join us to see what we have been working on and to give us your input. The main purpose for this session is to get feedback from TUF participants on the current release and prioritize items for future releases so that Intergraph can respond to your requirements. Please bring your proposals, share your user experiences, and participate in SPEL/SPI/S3D Cable Integration breakout session. We look forward to seeing you there!

Structure

10:30 -11:30 AM

Intergraph Sponsor: Joe Harrison

TUF Sponsor: Eng Teoh, URS

With Intergraph's purchase of the structural analysis tool, GT STRUDL, new opportunities are abundant in integrating this product and its functionality into the Smart 3D and CAESAR II applications. Join us as we talk about some of these innovative opportunities as well as review some of the new enhancements that have been added this past year. Your input is valuable in setting future priorities and business direction not only for GT STRUDL but also its incorporation into the Intergraph suite of products. This will also be an opportunity to personally meet members of these teams and exchange ideas.

Marine Content

12:30 – 1:30 PM

Intergraph Sponsor: Joe Baumer

In the Marine Content breakout session we will be presenting two new enhancements for v2014 R1 that will both reduce administrative burden and improve user productivity. The first enhancement is the Best Practice Stair and Ladder Wizards. These wizards are configurable to allow project standard stairs and ladders to be quickly and easily defined and saved for reuse without writing Visual Basic (VB) code. The wizards will create stairs and ladders as symbols or individual member parts that can be used to create welding and fabrication data. These wizards should be of interest to Plant and Offshore customers.

The second Marine Content enhancement is the Structure Detailing Rules Configuration Manager. The Configuration Manager is an administrative tool that will allow basic Smart Occurrence selection and parameter rule settings to be changed without editing and recompiling VB code. While currently only applicable to the Marine Structure Detailing rules, this tool is the path forward for most Smart 3D rule-based Smart Occurrence objects. This forum will provide an introduction to these new capabilities and an opportunity for you to ask questions and provide feedback.

New Environments

1:45 – 2:45 PM

Intergraph Sponsor: Joe Baumer

As a result of harmonizing our Smart 3D project suite for marine, plant, and material handling in V2014, several new environments are now available to all Smart 3D users including Compartmentation, Hole Management, Molded Forms, Planning, Structural Detailing, and Structural Manufacturing. This breakout session will provide a forum to let you share how you have integrated these new functionalities in your work processes and any improvements you'd like to see now that you have started executing these environments in typical plant workflows.

Materials Handling Environment

3:00 - 5:00 PM

Intergraph Sponsor: Barry Woodin

Please join us in the Material Handling breakout session, where we will start off with an update from Intergraph on new functionality in 2014 R1 release and future direction of Smart 3D for the Materials & Mining industry. Following the release update will have client presentations on a variety of M&M specific items, for example Chute and Conveyor layout. Finally we will have an open group discussion on current MHE functionality and how this fits the M&M industry.

ENGINEERING & SCHEMATICS TUFs

Agenda

| Instrumentation, Electrical & P&ID Combined TUF – Room 310 | |
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| Time | Topic |
| 08:00 a.m. | Introductions (John Dressel SPI, Earl Trindle SPEL and Fernando Murcia SP&ID TUF chairs) |
| 08:05 a.m. | Welcome to the Power & Marine for the Technical User Forum (Frank Joop) |
| 08:15 a.m. | Enhanced Smart Engineering (Frank Joop) Overview of the Engineering & Schematic plans and strategic direction. Intergraph PP&M is working to direct the solutions to open up business opportunities for our customers during the various economic cycles. |
| 08:30 a.m. | Engineering & Schematic (Meir Stein/Zur Bar) Configuration management – covering new enhancement planned from the Reference Data Synchronization Manager (RDSM) for the three main E&S products SP P&ID/SPEL and SPI that allows the Admin to push selected configuration from one plant to another plant. |
| | SmartPlant P&ID (Paras Trivedi) <ul style="list-style-type: none"> • SP P&ID engineer – An environment for Process engineers to perform their tasks. This session will cover the basic functionalities of SP P&ID Engineer which take advantage of data and rule driven solution. |
| | SmartPlant Instrumentation (Zur Bar) <ul style="list-style-type: none"> • Hook-Up's / Installation details – Will cover SPI hook-up module, using the Enhance Smart Report and all Bill of Material (BoM) management. |
| | SmartPlant Electrical (Meir Stein) <ul style="list-style-type: none"> • Design reuse - Often projects replicate themselves or redundant similar systems. Ability to import legacy data and drawing, a time saver • 2. Tighter Projects schedules - Typical cable block diagrams reduces design time and increases consistency. Ability to use typical cable block diagrams to produce project deliverables |
| 09:30 a.m. | Master Tag Registry (Allen Egnor) |
| 09:50 a.m. | SmartPlant Navigator (Ping Fang) |
| 10:10 a.m. | Break/Networking |
| 10:30 a.m. | SmartPlant Construction (Jason Dubose) |
| 10:50 a.m. | SmartPlant Foundation (Ben Parikh) |



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| 11:10 a.m. | SmartPlant Material (Marcelo Joaquim) |
| 11:20 a.m. | SmartPlant CR Ranking Presentation (Dennis Cooley) |
| 11:30 a.m. | SmartPlant 2D Products Forum (Zur Bar, Paras Trivedi, Meir Stein) |
| 12:00 p.m. | TUF lunch – Room 316/317 |
| 1:00 p.m. | Instrumentation, Electrical & Process Design breakout meetings |

Instrumentation Breakout Meeting

Abstract

The SmartPlant Instrumentation TUF Breakout session will focus on the demands of using SmartPlant Instrumentation in both the EPC and owner operator environments with emphasis on interfaces and integration. The session will review the CR ranking process and the use of SmartPlant Instrumentation with emerging wiring technologies. Other discussion items planned for this session include:

- Users experiences with SmartPlant Instrumentation
- Owner operator considerations with SmartPlant Instrumentation
- Communication between users and Intergraph representatives
- New capabilities and function of SmartPlant Instrumentation

Agenda

| Instrumentation TUF – Room 310 | |
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| Time | Topic |
| 1:00 p.m. | Opening remarks (SPI TUF Chair; John Dressel) <ul style="list-style-type: none"> • SmartPlant Instrumentation Out or Outside the Box |
| 1:15 p.m. | SmartPlant Instrumentation Status (Zur Bar) <ul style="list-style-type: none"> • SmartPlant Instrumentation release plans and schedules • SmartPlant Instrumentation 2015 new feature overview • SmartPlant Instrumentation 2015R1/2017 plans • SmartPlant Instrumentation future release plans |
| 1:45 p.m. | SmartPlant Instrumentation DDP Module (Ron Jackson) |
| 2:00 p.m. | PAS Integrity introduction (Nick Cappi) |
| 2:20 p.m. | SPInspector introduction (Louis Trujillo) |
| 2:40 p.m. | Break / Networking |



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| 3:00 p.m. | CAXperts introduction (Christine Rech) |
| 3:20 p.m. | Emerson SPI Interfaces (Sam Sivaskandan) |
| 3:40 p.m. | Endress+Hauser SPI Integration (Andreas Buchdunger) |
| 4:00 p.m. | Thomas Net introduction (Michael Sprague) |
| 4:20 p.m. | Open Q&A session |
| 4:30 p.m. | Formal meeting close / Networking |

Electrical Breakout Meeting

Abstract

The Electrical TUF breakout session allows current users of SmartPlant Electrical to share experiences, learn from others, and help the direction of the product in an open dialog setting. During this session, attendees will discuss the new functionality expected in the next release and workflows that can be enhanced with integration and automation layer.

Other discussion items planned for this session include:

- Users sharing experiences with SmartPlant Electrical
- Presentations from users on possibilities of using automation layer and other interfaces
- Exchange ideas and experiences among peers and Intergraph representatives
- Discuss and learn about new product capabilities delivered in recent releases

Agenda

| Electrical TUF – Room 311 | |
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| Time | Topic / Discussion Leader |
| 1:00 p.m. | Opening remarks (SPEL TUF Chair; Earl Trindle) |
| 1:15 p.m. | SmartPlant Electrical product update (Meir Stein, Intergraph) <ul style="list-style-type: none"> • SmartPlant Electrical 2015 release features • SmartPlant Electrical 2015R1/2017 release planned features |
| 2:00 p.m. | SmartPlant Electrical Reference Data (Earl Trindle) |
| 2:30 p.m. | Break / Networking |
| 2:45 p.m. | TUF member technical presentations for SmartPlant Electrical use and improvements <ul style="list-style-type: none"> • The New SPEL API, (Predraq Vasic from Fluor in Canada) • SPEL projects and Project Manager (Julian Hinstroza, Catch Engineering Canada) |



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| 3:45 p.m. | Forum discussion/update on SmartPlant Electrical issues planned for next release: <ul style="list-style-type: none"> Naming conventions for single core cable assemblies “Symbology” per different types of SLD’s (key, detailed, etc) Automated SLD’s – paradigm in updating changes in data drawing while maintaining last saved position |
| 4:15 p.m. | Open Q&A session |
| 4:30 | Formal meeting close / Networking |

Process Design & Engineering Breakout Meeting

Abstract

The Process Design & Engineering TUF meeting is open to all current users of Intergraph SmartPlant P&ID. The meeting will provide a forum to exchange ideas among fellow users and Intergraph representatives. During the meeting, TUF chairpersons will discuss the previous year’s activities and mention upcoming planned events. There will be an overview of upcoming releases for SmartPlant P&ID, followed by questions and answers.

Agenda

| Process Design & Engineering TUF – Room 308 | |
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| Time | Topic / Discussion Leader |
| 1:00 p.m. | Opening remarks (SmartPlant P&ID TUF Chair; Fernando Murcia) |
| 1:15 p.m. | SmartPlant P&ID product update (Intergraph) <ul style="list-style-type: none"> SmartPlant P&ID release plans and schedules including SP Process Engineering SmartPlant P&ID 2014 R1 overview SmartPlant P&ID 2014R2/2017 release planned features SmartPlant P&ID future release plans |
| 2:00 p.m. | SmartPlant P&ID in the Cloud (Fernando Murcia /Chiru Panuganty) |
| 2:30 p.m. | Break / Networking |
| 2:45 p.m. | TUF member technical presentations on SmartPlant P&ID use and improvements <ul style="list-style-type: none"> SmartPlant Piping & Instrument Diagram and SmartPlant Instrumentation Integration (Emeka Nwagbara, Fluor) SP P&ID Unique tagging within SPPID and use of P&ID in the integrated environment (Raj Ayyamperuma AMEC) |
| 3:45 p.m. | Forum discussion on specific SmartPlant P&ID items; |



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| | <ul style="list-style-type: none"> • Using SmartPlant P&ID in the Cloud • Bridge between FEED (PFD) and Detailed Design • SmartPlant P&ID Owner operator issues/Hybrid P&ID's • SmartPlant P&ID Integration issues • Additional topics |
| 4:15 p.m. | Open Q&A session |
| 4:30 | Formal meeting close / Networking |

INFORMATION MANAGEMENT & SPO TUF

The Information Management & Integration (IM&I) Technical User Forum (TUF) will conduct its annual review of the SmartPlant Foundation (SPF) and SmartPlant Enterprise for Owner Operators (SPO) solutions. Join fellow Information Management users as they meet face to face to exchange work process insight and experiences to help make everyone more productive. TUF attendees should be prepared to discuss their own project experiences during this interactive time and help set software development priorities for future releases.

Agenda

| Information Management & SPO TUF – Room 320 | |
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| Time | Topic |
| 08.30 a.m. | Opening Remarks & Introductions (John Kidd, Intergraph) |
| 08.40 a.m. | Regional TUF Activity – Regional TUF Chairs (John Kidd, Intergraph) |
| 09.00 a.m. | Product updates <ul style="list-style-type: none"> • SPF 5.2 and 5.3 with report management and enhanced concurrent engineering; • SPO with Handover between different versions, System Completions mobile and paper solutions; Core ICAX enhancements; • Fusion with new Quality Control and Explorer modules, a new Database Reader and Tag Attribute Management; • SPECP PBS management for SPEM. |
| 10.00 a.m. | Break |
| 10.15 a.m. | Major new product releases <ul style="list-style-type: none"> • ICC2 for multi company project collaboration; • MTR for tag registers and reporting; • SPO Fusion Link for structured data migration to SPO; • Smart Data Validator for data import, validation and load into running systems. |
| 12.00 p.m. | TUF lunch – Room 316/317 |
| 12.30 p.m. | Product roadmaps |



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| | <ul style="list-style-type: none"> • SPF Web, UX & Form enhancements, Centralised Schema Management and rollout, SP Cloud, mapping UX, CDW management; • SPO Electronic Dossiers, Handover usability and administration, System Completions graphical scoping and mobile support; • Fusion enhanced web portal, more data capture options, Fusion Link to SPO, QC workbench • SPECPC centralised PBS and User management. |
| 1.15 p.m. | Customer presentation |
| 1.30 p.m. | <p>Round table sessions (SPO/SPE/SPF/VTL/Fusion): a chance to provide input to product development plans and share experiences.</p> <p>Last year this was a big success and it has provided input to the product direction that you will see in the new releases and prototypes shown this year.</p> |
| 2.15 p.m. | Break |
| 2.30 p.m. | Round table sessions continued |
| 3.30 p.m. | Capture of Discussion Priorities and AOB (All) |
| 3.45 p.m. | Formal Meeting Close / Networking |

MATERIALS MANAGEMENT TUF

The SmartPlant Materials Technical User Forum (TUF) is open to all current users of the Intergraph SmartPlant Materials product suite. This TUF provides a forum for exchange of ideas between fellow users and Intergraph representatives. Benefits of TUF membership will be discussed, and new clients are encouraged to join. During the session, the previous year’s TUF activities and achievements will be reviewed. Changes in SmartPlant Reference Data, SmartPlant Materials, and Standard Database will be shown as an overview. A question-and-answer period will follow, and the session will close with the determination of action items for 2015-2016.

Agenda

| Materials Management TUF – Room 309 | |
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| Time | Topic |
| 08:30 a.m. | Meet & Greet |
| 09:00 a.m. | Introductions & Review of the Agenda (Andrew Jameson, Hatch) |
| 09:15 a.m. | TUF Organizational Meeting & Objectives |
| 09:40 a.m. | TUF Communication on LinkedIn |



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| 10:00 a.m. | Product Update SPRD SDB (Satish Hota, Intergraph) |
| 10:30 a.m. | Product Update SPMat Classic, Business Intelligence, SPMat Portal (Guido Hufer, Intergraph) |
| 11:00 a.m. | SmartPlant Materials / Reference Data Support (Ahmet Akin, Intergraph) |
| 11:30 a.m. | TUF lunch – Room 316/317 |
| 12:30 a.m. | Intergraph Business Update, Global and Regional |
| 01:00 p.m. | Product Update SPMat new modules(Guido Hufer, Intergraph) |
| 01:30 p.m. | Customer Presentations: Jackie Davis, SP3D/SPRD/PDS Spec Writer at Burns & McDonnell – 15min Stefan James, CBI Power’s SBOM process- 15 min |
| 02:00 p.m. | Panel Discussions |
| 04:15 p.m. | Wrap Up |

SMARTPLANT CONSTRUCTION & SPOOLGEN TUF

This TUF provides a forum for exchange of ideas between fellow users and Intergraph representatives. All current SPC and SmartPlant Spoolgen users are encouraged to attend and join fellow SPC and SmartPlant Spoolgen users as they meet face to face to exchange work process insight and experiences to help make everyone more productive.

Agenda

| SmartPlant Construction/SmartPlant Spoolgen TUF – room 303 | |
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| Time | Topic |
| 10:00 a.m. | Meet & Greet - Introductions & Review of the Agenda (Jason Dubose, Intergraph) |
| 10:15 a.m. | TUF Communication on LinkedIn |
| 10:30 a.m. | Piping Fabrication & Erection (David Myall, Intergraph) |
| 11:10 a.m. | Smart Yard |
| 11:30 a.m. | TUF lunch – Room 316/317 |
| 12:30 p.m. | SPC Update & Roadmap (Jason Dubose, Intergraph) |



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| 01:00 p.m. | Open Discussions |
| 02:30 p.m. | Wrap Up |

Reservations

To reserve your place at the SPC/Spoolgen TUF Meeting, please email jason.dubose@intergraph.com.